

Customer No.: 31561  
Application No.: 10/707,683  
Docket NO.: 11846-US-PA

### **AMENDMENT**

#### **In the Claims:**

1. (original) A chip package structure, comprising:

a carrier;

a chip, having an active surface with a plurality of bumps thereon, wherein the active surface of the chip is bonded to the carrier using a flip-chip bonding technique so that the chip and the carrier are electrically connected; and

an encapsulating material layer, covering the chip and the carrier and filling the bonding gap between the chip and the carrier, wherein the encapsulating material layer between the chip and the carrier has a first thickness and the encapsulating material layer on the chip has a second thickness such that the second thickness is between 0.5 ~ 2 times the first thickness.

2. (original) The chip package structure of claim 1, wherein maximum diameter of particles constituting the encapsulating material layer is smaller than 0.5 times the first thickness.

3. (original) The chip package structure of claim 1, wherein the package further comprises an array of solder balls attached to a surface of the carrier away from the chip.

4. (original) The chip package structure of claim 1, wherein the package further comprises a passive component attached and electrically to the carrier.

5. (original) The chip package structure of claim 1, wherein the carrier is selected from a group consisting of a package substrate and a lead frame.

Claims 6- 20 (withdrawn)